

Abstract

The present invention relates to a data carrier having an integrated circuit, and describes a method for producing data carriers. The data carrier has the form of a card in which an accordingly formed two-step recess is provided for incorporation of the carrier element. The carrier element comprises a substrate on which the integrated circuit is disposed. To be protected from mechanical loads at least the integrated circuit is surrounded by a casting compound, for example a casting resin. The carrier element is connected with the card body by means of a thermally activated adhesive layer under the action of heat and pressure. The adhesive layer is provided with an opening dimensioned in such a way that the casting compound is at least partly covered in its edge area by the adhesive layer when the carrier element is bonded to the card body.

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